

## RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					CODE	FACILITY
DS1100	A3	OCT '01	28532	0126	ATP (Amkor, PI)	DK114601AD	SOIC	4	0
DS1100	A3	JAN '02	28611	0132	ATP (Amkor, PI)	DK115002AK	SOIC	4	0
DS1803	A2	NOV '01	28555	0143	ATP (Amkor, PI)	DK122629AA	SOIC	4	0
DS1803	A2	APR '02	29503	0204	OSEP	DE113317AAB	SOIC	4	0
DS2118M	C1	MAR '02	28816	0143	ATK (Amkor, K)	DN120700AB	SSOP	4	0
DS21Q43	A3-	SEP '01	27877	0047	Stats	DC036714AA	LQFP	4	0
DS21S07	C1-	FEB '02	28805	0112	Carsem	DM048483AC	TSSOP	4	0
DS2502	C4	APR '02	29355	0220	OSEP	DE218054AEC	TSOC	4	0
DS80CH11	A4	DEC '01	28598	0113	ATK (Amkor, K)	DN036754AA	LQFP	4	0
DS87C520	A15-	FEB '02	28777	0206	ATP (Amkor, PI)	DK101111AA	PLCC	4	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28621	0201 Fastech	304930	Module w/SMT	300	100	1
DS12887	A2-	APR '02	29529	0219 Fastech	330288	Module w/Bent Fra	300	100	0
DS1990	J3-F	JUN '02	29484	0211 Fastech	320968-1	iButton F50w/IC's	500	77	2
DS1992	E7-F	JUN '02	29496	0220 Fastech	321281-1	iButton F50 w/Bum	500	77	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601AD	SOIC	300	40	0
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1000	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AK	SOIC	300	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1000	40	0
DS1803	A2	NOV '01	28559	0143	ATP (Amkor, PI)	DK122629AA	SOIC	300	40	0
DS1803	A2	NOV '01	28559	0143	ATP (Amkor, PI)	DK122629AA	SOIC	1000	40	0
DS1803	A2	APR '02	29507	0204	OSEP	DE113317AAB	SOIC	500	40	0
DS1803	A2	APR '02	29507	0204	OSEP	DE113317AAB	SOIC	1000	40	0
DS2118M	C1	MAR '02	28820	0143	ATK (Amkor, K)	DN120700AB	SSOP	300	80	0
DS2118M	C1	MAR '02	28820	0143	ATK (Amkor, K)	DN120700AB	SSOP	1000	80	0
DS21Q43	A3-	SEP '01	27881	0047	Stats	DC036714AA	LQFP	300	77	0
DS21Q43	A3-	SEP '01	27881	0047	Stats	DC036714AA	LQFP	1000	76	0
DS21S07	C1-	FEB '02	28809	0112	Carsem	DM048483AC	TSSOP	300	45	0
DS21S07	C1-	FEB '02	28809	0112	Carsem	DM048483AC	TSSOP	1000	45	0
DS2502	C4	APR '02	29358	0220	OSEP	DE218054AEC	TSOC	300	77	0
DS2502	C4	APR '02	29358	0220	OSEP	DE218054AEC	TSOC	1000	74	0
DS80CH11	A4	DEC '01	28602	0113	ATK (Amkor, K)	DN036754AA	LQFP	300	70	0
DS80CH11	A4	DEC '01	28602	0113	ATK (Amkor, K)	DN036754AA	LQFP	1000	69	0
DS87C520	A15-	FEB '02	28781	0206	ATP (Amkor, PI)	DK101111AA	PLCC	300	50	0
DS87C520	A15-	FEB '02	28781	0206	ATP (Amkor, PI)	DK101111AA	PLCC	1000	50	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	300	77	0
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS87C520	A15-	FEB '02	28783	0206 ATP (Amkor, PI)	DK101111AA	PLCC	336	50	0
DS87C520	A15-	FEB '02	28783	0206 ATP (Amkor, PI)	DK101111AA	PLCC	1000	50	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28564	0151 Dallas	304797	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '01	28564	0151 Dallas	304797	Module w/Hi Densit	1000	77	0
DS1990	J3-F	JUN '02	29483	0211 Fastech	320968-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	JUN '02	29483	0211 Fastech	320968-1	iButton F50w/IC's	1000	77	0
DS1992	E7-F	JUN '02	29495	0220 Fastech	321281-1	iButton F50 w/Bum	500	77	0
DS1992	E7-F	JUN '02	29495	0220 Fastech	321281-1	iButton F50 w/Bum	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28620	0201 Fastech	304930	Module w/SMT	48	200	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28618	0201 Fastech	304930	Module w/SMT		3	0
DS12887	A2-	APR '02	29527	0219 Fastech	330288	Module w/Bent Fra		3	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1643	C1	NOV '01	28562	0151 Dallas	304797	Module w/Hi Densit	3 0

## RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					CODE	FACILITY
DS1100	A3	OCT '01	28534	0126	ATP (Amkor, PI)	DK114601AD	SOIC	4	0
DS1100	A3	JAN '02	28613	0132	ATP (Amkor, PI)	DK115002AK	SOIC	4	0
DS1803	A2	NOV '01	28557	0143	ATP (Amkor, PI)	DK122629AA	SOIC	4	0
DS1803	A2	APR '02	29505	0204	OSEP	DE113317AAB	SOIC	4	0
DS2118M	C1	MAR '02	28818	0143	ATK (Amkor, K)	DN120700AB	SSOP	4	0
DS21Q43	A3-	SEP '01	27879	0047	Stats	DC036714AA	LQFP	4	0
DS21S07	C1-	FEB '02	28807	0112	Carsem	DM048483AC	TSSOP	4	0
DS2502	C4	APR '02	29357	0220	OSEP	DE218054AEC	TSOC	4	0
DS80CH11	A4	DEC '01	28600	0113	ATK (Amkor, K)	DN036754AA	LQFP	4	0
DS87C520	A15-	FEB '02	28779	0206	ATP (Amkor, PI)	DK101111AA	PLCC	4	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28619	0201 Fastech	304930	Module w/SMT		6	0
DS12887	A2-	APR '02	29528	0219 Fastech	330288	Module w/Bent Fra		6	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28563	0151	Dallas	304797	Module w/Hi Densit		6	0

# RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28622	0201	Fastech	304930	Module w/SMT	288	100	0
DS1230	A1-Y	JAN '02	28622	0201	Fastech	304930	Module w/SMT	960	100	0
DS1643	C1	NOV '01	28566	0151	Dallas	304797	Module w/Hi Densit	288	77	0
DS1643	C1	NOV '01	28566	0151	Dallas	304797	Module w/Hi Densit	960	77	0
DS1990	J3-F	JUN '02	29485	0211	Fastech	320968-1	iButton F50w/IC's	500	76	0
DS1990	J3-F	JUN '02	29485	0211	Fastech	320968-1	iButton F50w/IC's	1000	76	0
DS1992	E7-F	JUN '02	29497	0220	Fastech	321281-1	iButton F50 w/Bum	500	77	0
DS1992	E7-F	JUN '02	29497	0220	Fastech	321281-1	iButton F50 w/Bum	1000	77	0

# RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21Q43	A3-	SEP '01	27883	0047 Stats	DC036714AA	LQFP	100	40	0
DS80CH11	A4	DEC '01	28604	0113 ATK (Amkor, K)	DN036754AA	LQFP	100	44	0

# RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS87C520	A15-	FEB '02	28782	0206 ATP (Amkor, PI)	DK101111AA	PLCC	96	58	1

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS87C520	A15-	FEB '02	28778	0206	ATP (Amkor, PI)	DK101111AA	PLCC	3	239	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1100	A3	OCT '01	28533	0126	ATP (Amkor, PI)	DK114601AD	SOIC	3	238	0
DS1100	A3	JAN '02	28612	0132	ATP (Amkor, PI)	DK115002AK	SOIC	3	238	0
DS1803	A2	NOV '01	28556	0143	ATP (Amkor, PI)	DK122629AA	SOIC	3	241	0
DS1803	A2	APR '02	29504	0204	OSEP	DE113317AAB	SOIC	3	241	0
DS2118M	C1	MAR '02	28817	0143	ATK (Amkor, K)	DN120700AB	SSOP	3	238	4
DS21Q43	A3-	SEP '01	27878	0047	Stats	DC036714AA	LQFP	3	241	0
DS21S07	C1-	FEB '02	28806	0112	Carsem	DM048483AC	TSSOP	3	243	0
DS2502	C4	APR '02	29356	0220	OSEP	DE218054AEC	TSOC	3	151	0
DS80CH11	A4	DEC '01	28599	0113	ATK (Amkor, K)	DN036754AA	LQFP	3	244	1

## RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	APR '02	29530	0219	Fastech	330288	Module w/Bent Fra	274	100	0
DS12887	A2-	APR '02	29530	0219	Fastech	330288	Module w/Bent Fra	959	100	0
DS1803	A2	NOV '01	28560	0143	ATP (Amkor, PI)	DK122629AA	SOIC	274	77	0
DS1803	A2	NOV '01	28560	0143	ATP (Amkor, PI)	DK122629AA	SOIC	959	77	0
DS1803	A2	APR '02	29508	0204	OSEP	DE113317AAB	SOIC	500	77	0
DS1803	A2	APR '02	29508	0204	OSEP	DE113317AAB	SOIC	1000	76	0
DS21Q43	A3-	SEP '01	27882	0047	Stats	DC036714AA	LQFP	274	32	0
DS21Q43	A3-	SEP '01	27882	0047	Stats	DC036714AA	LQFP	959	32	0
DS21S07	C1-	FEB '02	28810	0112	Carsem	DM048483AC	TSSOP	274	77	0
DS21S07	C1-	FEB '02	28810	0112	Carsem	DM048483AC	TSSOP	959	77	0
DS80CH11	A4	DEC '01	28603	0113	ATK (Amkor, K)	DN036754AA	LQFP	274	31	0
DS80CH11	A4	DEC '01	28603	0113	ATK (Amkor, K)	DN036754AA	LQFP	959	31	0

# RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28538	0126	ATP (Amkor, PI)	DK114601AD	SOIC	168	40	0
DS1100	A3	JAN '02	28617	0132	ATP (Amkor, PI)	DK115002AK	SOIC	168	39	0
DS1803	A2	NOV '01	28561	0143	ATP (Amkor, PI)	DK122629AA	SOIC	168	37	0
DS1803	A2	APR '02	29509	0204	OSEP	DE113317AAB	SOIC	168	39	0
DS2118M	C1	MAR '02	28821	0143	ATK (Amkor, K)	DN120700AB	SSOP	168	73	0
DS21S07	C1-	FEB '02	28811	0112	Carsem	DM048483AC	TSSOP	168	34	0
DS2502	C4	APR '02	29359	0220	OSEP	DE218054AEC	TSOC	96	69	0